

EAST Search History

10/840049

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S63	1	10/840049	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/24 16:01
S64	0	200/20127825	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/24 16:02
S65	0	(200/20127825).CCLS.	USPAT	OR	OFF	2006/04/24 16:02
S66	2	"20020127825"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/24 16:03
S67	2	S66 and (copper or feature or alkaline or solution or atmosphere or oxidizing or surface or oxidation or sufficient or exposure or chemical or contaminating or wafer or semiconductor or newly or environment or queue or period or time)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/24 16:41
S68	792	contamination and oxidation and copper and (alkaline adj solution)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/24 16:31
S69	1	S68 and atmosphere and exposure and wafer and environment and queue	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/24 16:27
S70	3	contamination and oxidation and copper and (alkaline adj solution) and surface and (substantial adj exposure)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/24 16:32

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S71	3	S70 and (copper or feature or alkaline or solution or atmosphere or oxidizing or surface or oxidation or sufficient or exposure or chemical or contaminating or wafer or semiconductor or newly or environment or queue or period or time)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/24 16:35
S72	3	S71 and (copper or feature or exposing or surfaces or ammonia or hydroxylate or sufficient)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/24 16:41
S73	2	S66 and (copper or feature or alkaline or solution or atmosphere or oxidizing or surface or oxidation or sufficient or exposure or chemical or contaminating or wafer or semiconductor or newly or environment or queue or period or time)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/24 16:41
S74	2	S73 and (copper or feature or exposing or surfaces or ammonia or hydroxylate or sufficient)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/24 16:41